

REV.	EQUNO.	MODIF/CONTENT	DATE
A0		NEW	2017/10/17

Specification

MATERIAL:

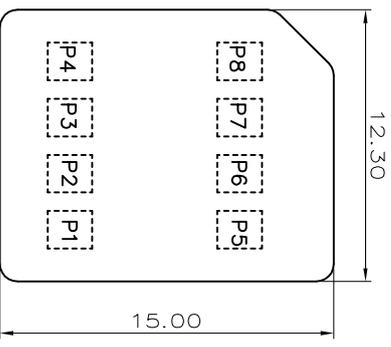
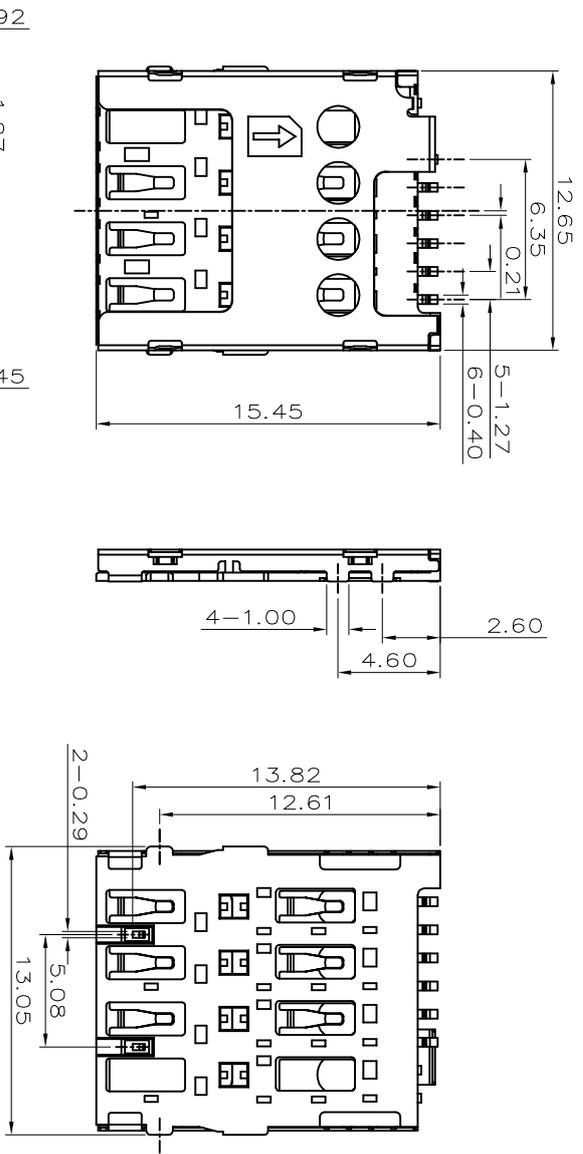
Insulator: LCP High Temperature Thermoplastic, UL 94V-0
 Contact: C5210
 SHEL: S05

PLATING:

Contact: Plated 50u" Ni Over Contact Au In, Pad Au In
 Shell: Plated 50u" Ni Overall, Pad Au In

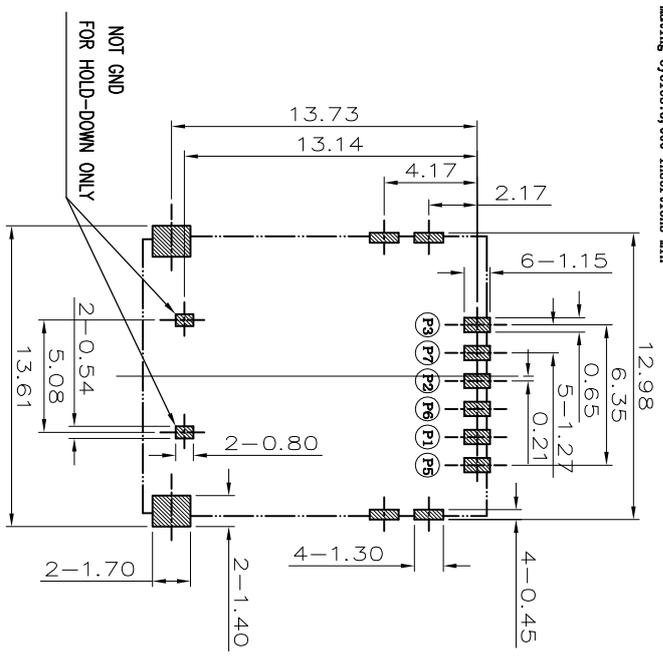
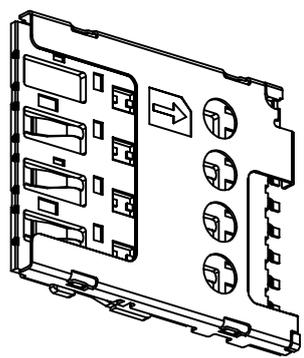
Electrical:

Current Rating : 0.5amps max
 Voltage Rating : 5V AC/DC
 Ambient Temperature Range : -40° C~+85° C
 Storage Temperature Range : -40° C~+85° C
 Ambient Humidity Range : 5% R.H. Max.
 Contact Resistance: 10mΩMax.
 Insulation Resistance: 1000MΩMin./500VDC
 Mating Cycles: 10,000 Insertions
 Retlow peak temp.: 280° C ±5° C, 3*5 S
 Mating Cycles: 3,000 Insertions Min



Pin1:VCC
 Pin2:RST
 Pin3:CLK
 Pin4:Reserved
 Pin5:GND
 Pin6:VPP
 Pin7:I/O
 Pin8:Reserved

MICRO SIM CARD



RECOMMENDED PCB LAYOUT
 TOLERANCE: ±0.05

GENERAL TOLERANCE		DWG NO.	XNT-SIM145-129	APPD:	COOO	Scale	1:1
X±0.45	x:±5'	Title	1.45H.MICRO SIM CARD CONNECTOR	CHKD:	AG	UNIT	mm
X±0.35	x'±2'	Part NO.	XNT-SIM145-129	DR:	JEFF		
.XX±0.25	.xx'±1'			Date:	2021/06/11		
.XXX±0.15	.xxx'±0.5'						
SHEET	1/2						

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